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 TI Composite **solders** and their manufacture for high-temperature
 uses
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 SO Jpn. Kokai Tokkyo Koho, 6 pp.
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AB The **solders** consist of **solder** materials contg.
 powders, and the **solder** materials comprise **Sn** alloys
 contg. 5-15% **Sb** and 2-15% **Ag**. The process comprises
 cold-working the **solder** materials. The **solders** have
 high ductility at 170.degree. and cold-workability and are esp. suitable
 for bonding parts in semiconductor devices used at high temp.